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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Manuel A. Quevedo-Lopez, et al.

Docket No.: TI-36376

Serial No.: 10/726,987

Art Unit: 2822

Filed: December 3, 2003

Examiner: Toniae M. Thomas

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For: Top Surface Roughness Reduction of High-K Dielectric Materials Using Plasma Based Processes

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